

Plaskon S-7

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is a state-of-the-art, low stress epoxy encapsulant designed for packaging stress-sensitive semiconductor devices. It offers end users superior value-in-use due to a balanced mix of properties.

General Information			
Features	Semi-conductive		
	Laser marking		
	Good formability		
	Excellent appearance		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.82	g/cm ³	ASTM D792
Molding Shrinkage - Flow	0.37	%	ASTM D955
Mechanical	Nominal Value	Unit	Test Method
Tensile Strength	0.00621	MPa	ASTM D638
Flexural Modulus	1.24	MPa	ASTM D790
Flexural Strength (21°C)	0.0103	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	150	°C	ASTM E1356
CLTE - Flow	1.7E-5	cm/cm/°C	ASTM D696
Thermal Conductivity	16	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	5.0E+15	ohms · cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.80		ASTM D150
Dissipation Factor (1 kHz)	2.0E-3		ASTM D150
Arc Resistance	180	sec	ASTM D495
Flammability	Nominal Value	Unit	Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	32	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: 5°C Life @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 months Life @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 days Life @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 days Spiral Flow, 175°C, 1000 psi: 85 to 115 cm Automatic Orifice Viscosity, 175°C, 1000 psi, 1 mm die length, 1/2 mm diameter: 17 Pascal sec Ram Follower Gel Time, 177°C: 13 to 21 sec Ash Content: 73.4 % Hydrolyzable Halides: <1 ppm Cull Hot Hardness, Shore D, 90 sec, 175°C: 75 Arc Resistance, 110v AC 180 sec All test specimens are transfer molded and post cured for 4 hours at 175°C
Linear Thermal Expansion, Alpha 1: 17 cm⁻⁶/cm/°C
Linear Thermal Expansion, Alpha 2: 45 cm⁻⁶/cm/°C

Injection instructions

Resin Transfer Molding:

Preheat Temperature: 85 to 95°C

Molding Temperature: 170 to 185°C

Molding Pressure: 900 to 1200 psi

Cure Time, 177°C: 1 to 2 min

Post Mold Cure Time, 175°C: 4 to 12 hr

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